



Low Cost Lead-Free Soldering Technology to Improve Competitiveness of European SME

The electronics industry in Europe is about to experience one of the biggest single changes since it started. The Restriction of the use of certain of Hazardous Substances (RoHS) Directive, due to be effective in July 2006, will mean that many parts of the Industry will have to change from tin/lead solder used to join the electronic components to the printed circuit boards (PCB) to a lead-free solder (LFS).

Due to these restrictions, it is quite important to make aware and prepare SMEs for the replacement of the existing soldering technology by other using LFS.

LEADOUT, Low Cost Lead-Free Soldering Technology to Improve the Competitiveness of European SMEs, is one of the largest European funded Projects, on lead-free technologies under the scope of 6th Framework SME oriented activities. It is a three year project and the consortium, comprising 31 partners from 10 European Countries, (11 Industrial Associations, 16 SME's and 4 Research Institutes), had its kick-off meeting in October 2004.

The main objective of the project is to provide technical support to a wide range of SMEs spread all over Europe in the development of technological solutions for the problems resulting from the replacement of tin-lead solders in the electronics industry. The project also covers environmental impact and life cycle evaluation as well as lead free process benchmarking.

The project website is available at the following address: www.leadoutproject.com

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